

<<芯片和系统的电源完整性建模与设计>>

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作者：Madhavan Swaminathan

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内容概要

本书包括电源完整性设计和建模两部分内容，重点在建模方面。全书分五章，涵盖了从基础知识到高级应用所需了解的各个细节。书中通过真实的案例分析和可下载的软件实例，描述了当今高效电源分配和噪声最小化的设计与建模的前沿技术，其中很多例子可以进行再仿真实现，这些可以用来评估常用的商用软件的准确性和速度。

《芯片和系统的电源完整性建模与设计(影印版)》适合研究电源完整性的学生、学者及工程师使用。

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